EQUIPMENT FOR SEMICONDUCTOR WAFER PROCESSING
&
ADVANCED PACKAGING

*CUSTOM ENGINEERED EQUIPMENT MANUFACTURING FOR OVER 25 YEARS*

Think Innovation For The Future

Teikoku Taping System is an innovative leading supplier for the semiconductor industry. Our portfolio covers a comprehensive range of products and solutions for Mid-end and Back-end semiconductor manufacturing.

A leading equipment supplier for **Dry Film Resist** *applications*
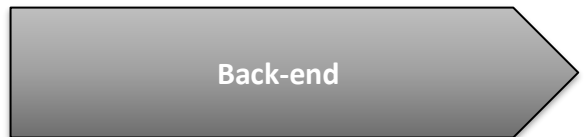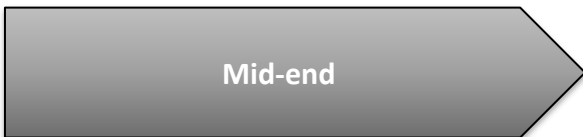
Products
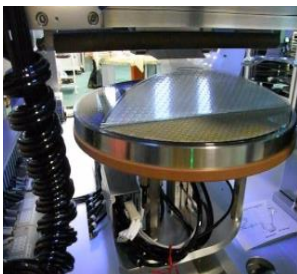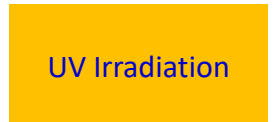
Tape Laminator　　　Tape Remover　　　　Wafer Mounter　　　UV Irradiation

Process Field

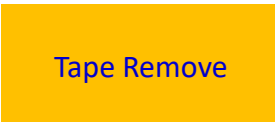Mid-end　　　　　　　　　　　Back-end

Segments

Tape Lamination　　Tape Remove　　　Wafer Mount　　　UV Irradiation
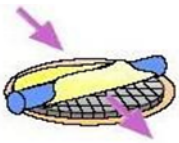
Tape Lamination

Fully Automatic Tape Lamination

Automatic wafer transfer, alignment, tape lamination, cutting

Ask us about -DRY FILM RESIST- applications.

Two methods available for cutting tape to best match the individual requirements. Blade cut or Laser.

Recipe controlled heat options to provide best tape application parameters settings for a wide variety of tape vendors.

Vacuum Lamination also available for NCF lamination, for wafers with topography features such as Flip Chip and TSV processed wafers.

		DXL2-800 Series	EXL2-1200 Series
		Standalone Tape Lamination for 8 inch	**Standalone Tape Lamination for 12 inch**
Applicable Wafer Size		4, 5, 6 and 8 inch	12 inch 8 inch (Option)
Selectable Cutting Type		Blade or Laser	Blade or Laser
Utilities	Dimensions (W x D xH) mm	1250 x 1400 x 2200	1350 x 1750 x 2200
	Inch	50 x 55 x 87	53 x 69 x 87
	Weight Kg	Approx. 800	Approx. 1000
	Lbs	Approx. 1770	Approx. 2200
	Power	200 - 240V, Single Phase	200 - 240V, Single Phase

☐ Semi-automatic tool; SXL model available
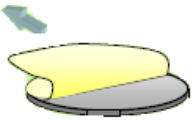
Tape Remover

Fully Automatic Tape Remover

Automatic wafer transfer, alignment, tape removing

Just to name a few of the multiple functions available on the TTS Tape Removing tools:
-Adjustable removing speed
-Adjustable removing angle
-Thin wafer handling
-Inline UV Irradiation System

The UV tape removal feature provides Auto UV Intensity Calibration. UV exposure provided by LED which provides better uptime due to longer LED lifetime.

		DXR2-800 Series Standalone Tape Remover for 8 inch	EXR2-1200 Series Standalone Tape Remover for 12 inch
Applicable Wafer Size		4, 5, 6 and 8 inch	12 inch 8 inch (Option)
Selectable Removing Type		Sticky or Heat Seal	Sticky or Heat Seal
Inline UV Irradiation Lamp Type		LED	LED
Utilities	**Dimensions**(W x D xH) mm	1250 x 1400 x 2000	1350 x 1750 x 2000
	Inch	50 x 55 x 79	53 x 69 x 79
	Weight Kg	Approx. 600	Approx. 1000
	Lbs	Approx. 1350	Approx. 2200
	Power	200 - 240V, Single Phase	200 - 240V, Single Phase

☐ Semi-automatic tool; SXR model available

Wafer Mounting

Fully Automatic Dicing Tape Wafer Mounter

Automatic wafer transfer, alignment, wafer mounting with Dicing frame, removing protective tape

Thin wafer handling capability of TTS Wafer Mounting tools are top performers in the industry.

With the option of thin wafer handling special end effector, the range of thin, ultra thin and warped wafers is a major plus for our tools.

			CXM-800/1200	EXM-800/1200
			Standalone Wafer Mounter	**Standalone Multifunction Wafer Mounter**
Applicable Wafer Size			Up to 12inch	8 and 12 inch (EXM-1200) 6 and 8 inch (EXM-800)
Selectable Removing Type			N/A	Sticky or Heat Seal
UV Irradiation Lamp Type			LED	LED
Dicing Tape Type			RCT or Pre-Cut	RCT or Pre-Cut
Utilities	Dimensions(W x D xH)	mm	1860 x 1200 x 1860	1900 x 2500 x 1900
		Inch	73 x 47 x 73	75 x 100 x 75
	Weight	Kg	Approx. 1000	Approx. 1800
		Lbs	Approx. 2200	Approx. 3970
	Power		200 - 240V, Single Phase	200 - 240V, Single Phase

☐ Semi-automatic tool; STM model available
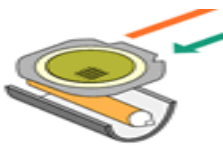
UV Irradiation

Fully Automatic UV Irradiation for UV Dicing Tape

Automatic wafer transfer, UV irradiation for UV Dicing tape

TTS UV Irradiation equipment was designed with simplicity in mind for greater MTBF and MTTR for a low cost of ownership.

The UV intensity and exposure is controlled in real time and automatically adjusts the exposure to provide the proper exposure dosage limits which are set in recipe control.

			EXR-800FMUV Series **Standalone UV Irradiation for 8 inch**	EXR-1200FMUV Series **Standalone UV Irradiation for 12 inch**
Applicable Wafer Size			4, 5, 6 and 8 inch	12 inch 8 inch (Option)
Applicable Dicing Frame			6 and 8 inch	8 and 12 inch
UV Irradiation Lamp Type			Metal Hydride (COLD UV) or LED	Metal Hydride (COLD UV) or LED
Utilities	**Dimensions**(W x D xH)	mm	1250 x 1250 x 1800	1250 x 1250 x 1800
		Inch	50 x 50 x 72	50 x 50 x 72
	Weight	Kg	Approx. 500	Approx. 500
		Lbs	Approx. 1100	Approx. 1100
	Power		200 - 240V, Single Phase	200 - 240V, Single Phase

☐ Semi-automatic tool; TMS model available
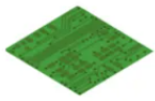
Advanced Packaging

Fully Automatic Panel/Substrate Lamination and Custom Solutions

Automatic lamination, tape/frame mounting, and custom functions.

Specialty tapes and films – carrier bonding, protective barriers – are enabling many advanced packaging processes.

We now offer panel lamination and panel mounting to dicing tape, as well as custom solutions. We can integrate UV irradiation, de-bonding, de-taping, and other functions, per customer requirement.
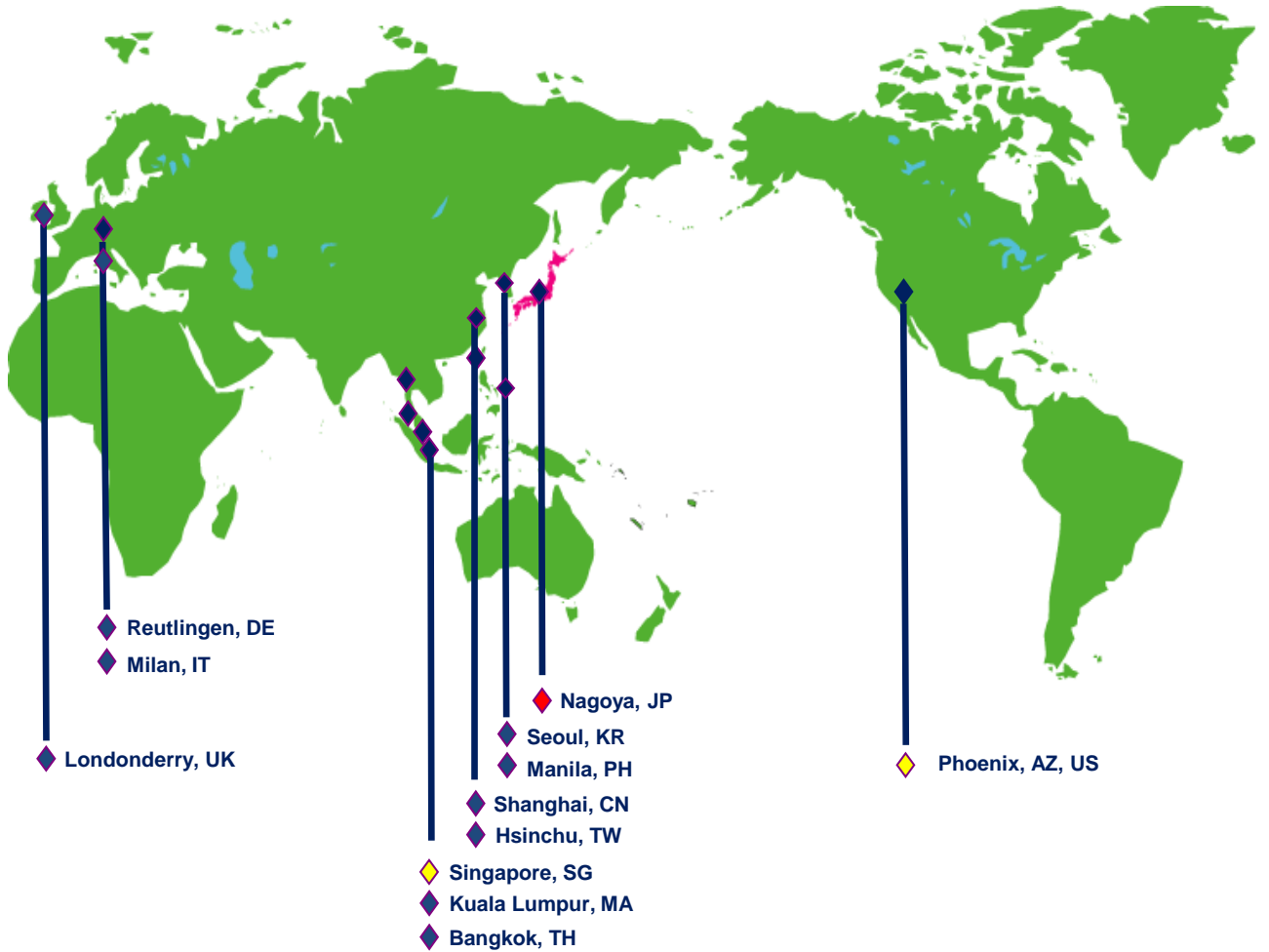
	CPL-300CS Standalone Multifunction Panel Laminator	CXM-800CS-PNL Standalone Multifunction Panel Mounter
Applicable Substrate/Panel Size	Up to 300 x 150 mm	Up to 300 x 150 mm
Applicable Tape types	Multiple – please inquire	UV or None UV Dicing Tape
Cutting Type	Blade	RCT or Pre-Cut
Options	Tape Removal, UV Irradiation, Vacuum Lamination and Other	Barcode Reader and Printer
Utilities — **Dimensions**(W x D xH) mm	1860 x 1200 x 1900	1900 x 1410 x 1900
Inch	73 x 47 x 75	75 x 56 x 75
Weight Kg	Approx. 1200	Approx. 1200
Lbs	Approx. 2650	Approx. 2650
Power	200 - 240V, Single Phase	200 - 240V, Single Phase

☐   Semi-automatic tools available

Reutlingen, DE
Milan, IT
Londonderry, UK
Nagoya, JP
Seoul, KR
Manila, PH
Shanghai, CN
Hsinchu, TW
Singapore, SG
Kuala Lumpur, MA
Bangkok, TH
Phoenix, AZ, US

◆ **Headquaters**

◇ **Subsidiary**

◆ **Sales representative**

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